Unit: mm

TOSHIBA Field Effect Transistor Silicon N Channel MOS Type (π-MOSV)

2SK2750

Chopper Regulator, DC-DC Converter and Motor Drive Applications

• Low drain–source ON resistance : RDS (ON) = 1.7 Ω (typ.) • High forward transfer admittance : $|Y_{fs}| = 3.0 \text{ S}$ (typ.) • Low leakage current : IDSS = 100 μ A (max) (VDS = 600 V) • Enhancement mode : Vth = 2.0~4.0 V (VDS = 10 V, ID = 1 mA)

Absolute Maximum Ratings (Ta = 25°C)

Characteristics		Symbol	Rating	Unit	
Drain-source voltage		V_{DSS}	600	V	
Drain-gate voltage (R _{GS} = 20 kΩ)		V_{DGR}	600	V	
Gate-source voltage		V_{GSS}	±30	V	
Drain current	DC (Note 1)	I _D	3.5	Α	
Diain current	Pulse (Note 1)	I _{DP}	14	Α	
Drain power dissipatio	n (Tc = 25°C)	PD	35	W	
Single pulse avalanche energy (Note 2)		E _{AS}	201	mJ	
Avalanche current		I _{AR}	3.5	Α	
Repetitive avalanche energy (Note 3)		E _{AR}	3.5	mJ	
Channel temperature		T _{ch}	150	°C	
Storage temperature range		T _{stg}	-55~150	°C	

Weight: 1.9 g (typ.)

Note: Using continuously under heavy loads (e.g. the application of high temperature/current/voltage and the significant change in temperature, etc.) may cause this product to decrease in the reliability significantly even if the operating conditions (i.e. operating temperature/current/voltage, etc.) are within the absolute maximum ratings. Please design the appropriate reliability upon reviewing the Toshiba Semiconductor Reliability Handbook ("Handling Precautions"/Derating Concept and Methods) and individual reliability data (i.e. reliability test report and estimated failure rate, etc).

Thermal Characteristics

Characteristics	Symbol	Max	Unit
Thermal resistance, channel to case	R _{th (ch-c)}	3.57	°C/W
Thermal resistance, channel to ambient	R _{th (ch-a)}	62.5	°C/W

Note 1: Ensure that the channel temperature does not exceed 150°C.

Note 2: V_{DD} = 90 V, T_{ch} = 25°C (initial), L = 28.8 mH, R_{G} = 25 Ω , I_{AR} = 3.5 A

Note 3: Repetitive rating: pulse width limited by maximum channel temperature

This transistor is an electrostatic-sensitive device.

Please handle with caution.



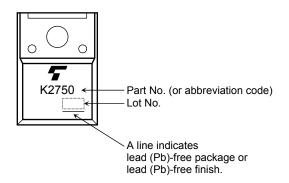
Electrical Characteristics (Ta = 25°C)

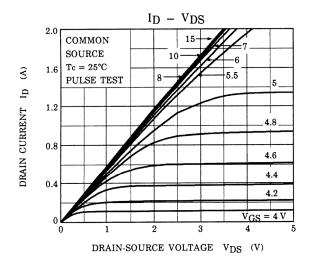
Charac	cteristics	Symbol	Test Condition	Min	Тур.	Max	Unit
Gate leakage cu	irrent	I _{GSS}	V _{GS} = ±25 V, V _{DS} = 0 V	_	_	±10	μΑ
Gate-source bro	eakdown voltage	V (BR) GSS	I _G = ±10 μA, V _{DS} = 0 V	±30	_	_	V
Drain cut-off cu	rrent	I _{DSS}	V _{DS} = 600 V, V _{GS} = 0 V	_	_	100	μA
Drain-source br	eakdown voltage	V (BR) DSS	I _D = 10 mA, V _{GS} = 0 V	600	_	_	V
Gate threshold v	voltage	V _{th}	V _{DS} = 10 V, I _D = 1 mA	2.0	_	4.0	V
Drain-source O	N resistance	R _{DS} (ON)	V _{GS} = 10 V, I _D = 1.8 A	_	1.7	2.2	Ω
Forward transfe	r admittance	Y _{fs}	V _{DS} = 10 V, I _D = 1.8 A	2.0	3.0	_	S
Input capacitano	e	C _{iss}		_	800	_	
Reverse transfer capacitance		C _{rss}	V _{DS} = 25 V, V _{GS} = 0 V, f = 1 MHz	_	6	_	pF
Output capacitance		Coss		_	65	_	
Switching time	Rise time	t _r	V_{GS} $0V$ $0V$ $0V$ $0V$ $0V$ $0V$ $0V$ $0V$	_	15	_	
	Turn-on time	t _{on}		_	50	_	- ns
	Fall time	t _f		_	15	_	
	Turn-off time	t _{off}		_	85	_	
Total gate charg plus gate-drain)		αg			20		
Gate-source charge		Q _{gs}	$V_{DD} \approx 400 \text{ V}, V_{GS} = 10 \text{ V}, I_D = 3.5 \text{ A}$		10		nC
Gate-drain ("miller") Charge		Q _{gd}			10	_	

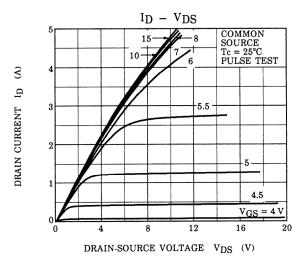
Source-Drain Ratings and Characteristics (Ta = 25°C)

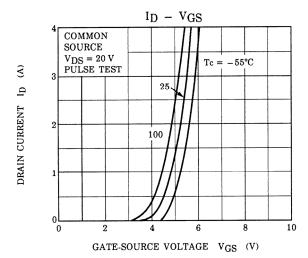
Characteristics	Symbol	Test Condition	Min	Тур.	Max	Unit
Continuous drain reverse current (Note 1)	I _{DR}	_	_	_	3	Α
Pulse drain reverse current (Note 1)	I _{DRP}	_	_	_	14	Α
Forward voltage (diode)	V _{DSF}	I _{DR} = 3.5 A, V _{GS} = 0 V	_	_	-1.7	V
Reverse recovery time	t _{rr}	I _{DR} = 3.5 A, V _{GS} = 0 V		1400	_	ns
Reverse recovery charge	Q _{rr}	dl _{DR} / dt = 100 Å / μs	_	9	_	μC

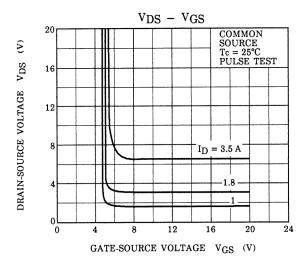
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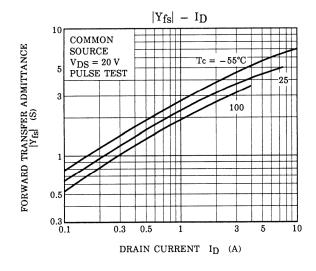


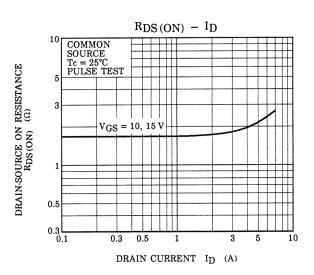




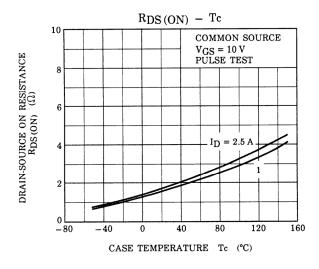


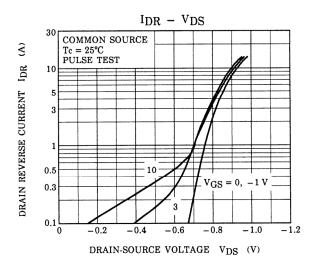


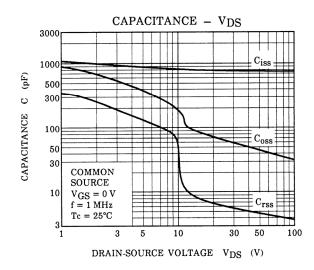


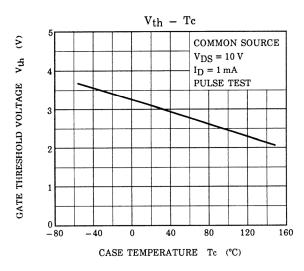


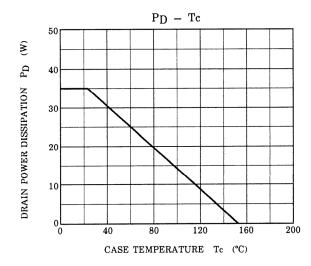
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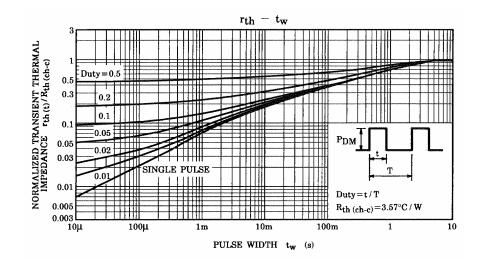


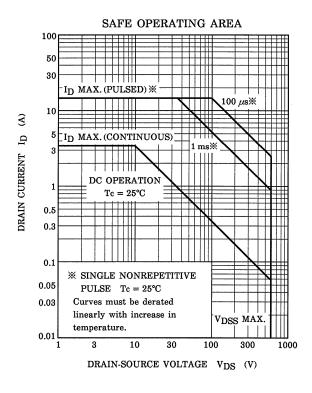


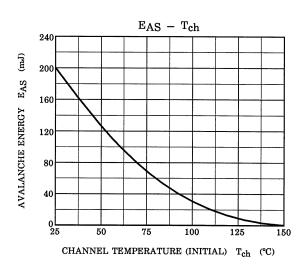


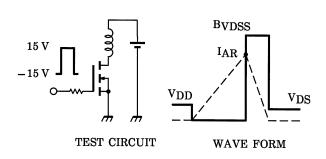












$$R_G$$
 = 25 Ω
 V_{DD} = 90 V, L = 28.8 mH

$$EAS = \frac{1}{2} \cdot L \cdot I^2 \cdot \left(\frac{B_{VDSS}}{B_{VDSS} - V_{DD}} \right)$$

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20070701-EN

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